

EC360 DIAMOND

Thermal Paste Series

The EC360® DIAMOND series means High Performance. A compound of highly thermal conductive material, enables an outstandingly high thermal conductivity of 11W/mK. Engineered with a focus on high performance, it is the perfect choice for cooling GPUs and CPUs in extreme cooling scenarios, like overclocking.

In short, it ensures efficient dissipation of heat in any use case. At the same time, it can be safely applied, it is not electrically conductive, remains easy to spread and is highly durable. Low bleed, non-flowing and low evaporation mean it is long-lasting, will stay in place and not dry out over time.

Types and Configurations

* Custom configurations are available upon request, for worldwide industrial inquiries please contact us at: sales@extremecool360.com

Type*	Available sizes*
Tube	1 g, 4 g, 20 g

Technical Properties

Properties	Unit	Value	Test method
Color	-	grey	Visual
Thermal Conductivity	W/mK	11.0	ASTM D5470
Thermal Resistance	°C-in ² /W	0.0013	ASTM D5470
Specific Gravity	g / cm ³	3.2	ASTM D 792
Evaporation(150°C/24h)	%	0.15	FED STD 791
Volume Impedance	Ohm-cm	3.0 x10 ¹³	ASTM D 257
Viscosity	cP	15000	-
Dielectric Constant	1Mhz	3.0	ASTM D 150
Usable Temperatures	°C	-30 - 240	EN 344

Installation Recommendation

- Clean surfaces from dirt and other possible residue. If applicable, isopropyl 90% alcohol is recommended to ensure a clean surface.
- Apply the product, for example by applying a drop in the center of the chip.
- Install the heatsink. Ideally the drop should have spread now, covering the entire chip in a thin layer of thermal paste without any air bubbles.
- If the result is not satisfactory apply again in a different quantity until the desired result has been achieved.

Disclaimer Properties of the products may be revised due to changes in the manufacturing process. The property values in this document are not guaranteed. This product is made of silicone, this means silicone oil may exude from the product and low molecular siloxane may vaporize depending on operating conditions. This product is designed and manufactured for industrial use only. Never use this product for medical, surgical purposes and/or other purposes. Never use this product for the purpose of implants, or any other purposes by which a part of the product remains in the human body. Before using safety must be evaluated and verified by the purchaser. Contents described here do not guarantee performances and qualities required for the purchaser's specific purposes. Statements concerning possible or suggested uses made herein may not be relied upon.

